

FORM PTO-1449 U.S. DEPARTMENT OF COMMERCE				ATTY. DOCKET NO. NSL-029		SERIAL NO. Not Yet Assigned	
LIST OF PRIOR ART CITED BY APPLICANT (Use several sheets if necessary)				APPLICANT Dong Yu et al.			
				FILING DATE Herewith		GROUP Not Yet Assigned	
U.S. PATENT DOCUMENTS							
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
/JB/	A	6,472,459	10/29/2002	Morales et al.	524	439	1/16/2001
	B	6,454,886	9/24/2002	Martin et al.	149	2	11/23/1999
	C	6,323,417	11/27/2001	Gillespie et al.	136	262	9/28/1999
	D	6,268,014	7/31/2001	Eberspacher et al.	427	74	10/2/1997
	E	6,228,904	5/8/2001	Yadav et al.	523	210	5/22/1998
	F	6,127,202	10/3/2000	Kapur et al.	438	47	7/2/1998
	G	6,124,041	9/26/2000	Aoude et al.	428	472	3/11/1999
	H	6,126,740	10/3/2000	Schulz et al.	117	4	1/27/1998
	I	5,985,691	11/16/1999	Basol et al.	438	95	5/16/1997
	J	5,728,231	5/15/1996	Negami et al.	148	33	5/15/1996
	K	5,567,469	10/22/1996	Wada et al.	427	74	6/1/1996
	L	5,538,903	7/23/1996	Aromoto et al.	438	94	11/18/1994
	M	5,445,847	8/29/1995	Wada et al.	427	74	5/27/1994
/JB/	N	20020006470	2/17/2002	Eberspacher et al.	427	216	7/3/2001
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION
OTHER PRIOR ART (Including Author, Title, Date, Pertinent Pages, Etc.)							
/JB/	O	S. L. Castro et al. "Nanocrystalline Chalcopyrite Materials (CuInS <sub>2</sub> and CuInSe <sub>2</sub> ) via Low-Temperature Pyrolysis of Molecular Single-Source Precursors" <i>Chem. Mater.</i> , vol. 15, pp 3142-3147, 2003					
	P	B. A. Ridley et al, "All-Inorganic Field Effect Transistors Fabricated by Printing" in <i>Science</i> , vol. 286, pp 746-749, 22 October 1999					
	Q	J. Zhu, et al, "General Sonochemical Method for the Preparation of Nanophasic Selenides: Synthesis of ZnSe Nanoparticles" in <i>Chem. Mater.</i> 2000, vol. 12, pp 73-78					
	R	B. Li, et al. "Synthesis by a Solvothermal Route and Characterization of CuInSe <sub>2</sub> Nanowhiskers and Nanoparticles" in <i>Advanced Materials</i> , vol. 11, no. 17, pp 1456-1459, 1999, Wiley-VCH Verlag GmbH					
	S	P. Sen, et al. "Preparation of Cu, Ag, Fe and Al nanoparticles by the exploding wire technique" in <i>Proc. Indian Acad. Sci. (Chem. Sci.)</i> , Vol. 115, Nos 5 & 6, pp 499-508, Oct-Dec 2003, Indian Academy of Sciences					
	T	M. A. Malik et al. "A Novel Route for the Preparation of CuSe and CuInSe <sub>2</sub> Nanoparticles" in <i>Advanced Materials</i> , vol. 11, No. 17, pp 1441- 1444, WILEY-VCH Verlag GmbH, Weinheim					
/JB/	U	K. K. Banger et al. "Synthesis and Characterization of the First Liquid Single-Source Precursors for the Deposition of Ternary Chalcopyrite (CuInS <sub>2</sub> ) Thin Film Materials" in <i>Chem. Mater.</i> , vol. 13, 3827-3829, 2001, American Chemical Society.					
EXAMINER /Jeffrey Barton/				DATE CONSIDERED 12/20/2007			
* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							

<b>INFORMATION DISCLOSURE STATEMENT</b>  <b>PTO-1449</b>	<b>ATTY. DOCKET NO.</b> NSL-029	<b>SERIAL NO.</b> 10/782,017
	<b>APPLICANT</b> Brian M. Sager, et al.	
	<b>FILING DATE:</b>	<b>GROUP:</b>
<b>SHEET 1 OF 1</b>		

<b>EXAMINER'S INITIALS</b>	<b>CITE NO.</b>	<b>PATENT NO.</b>	<b>PUBLICATION DATE MM-DD-YYYY</b>	<b>NAME</b>
/JB/	A	6,107,562	08-22-2000	Hashimoto, et al.

**NON-PATENT LITERATURE DOCUMENTS**

<b>EXAMINER'S INITIALS</b>	<b>CITE NO.</b>	Include name of the author (in CAPITAL LETTERS), title of article, title of item (book, journal, serial, etc...), date, pages, volume issue number, publisher, city/state where published	<b>Translation</b>	
			<b>YES</b>	<b>NO</b>

<b>EXAMINER</b> /Jeffrey Barton/	<b>DATE CONSIDERED</b> 12/20/2007
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